

## CLAIMS

5           1.- "DESIGN FOR ELECTRONIC COMPONENT PATTERNS OVER 400  
MICRON LAYERS ON PRINTED CIRCUITS", consisting of a dielectric  
material substrate (11) over which, the conducting material  
tracks (12) are drawn and constructed, such as copper,  
aluminium or similar, depositing between said tracks (12) an  
10       adhesive material (14) with the purpose of interlocking to  
electronic components (13) as a preliminary step, so that once  
they are adhered to the conducting material track (12), they  
receive the corresponding soldering material (15) in a wave  
soldering process, characterised in that in the printed  
15       circuits (10) the layer of conducting material or copper track  
(12) will be  $h_2$  greater than  $h_1$  and the corresponding pads of  
width  $a_1$  will have a greater width  $a_2$ .

          2.- "DESIGN FOR ELECTRONIC COMPONENT PATTERNS OVER 400  
MICRON LAYERS ON PRINTED CIRCUITS" in accordance with claim 1,  
20       characterised in that the conducting parts (13.2) of  
electronic components (13) will have a width  $a_2$  when the  
copper conducting layers (12) have a height  $h_2$  greater than  
105 microns.